

L Number	Hits	Search Text	DB	Time stamp
1	2528010	die chip semiconductor ic (integrated adj circuit) dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:43
2	1843861	sheet (silicone with rubber) silicone	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:43
3	351061	heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:44
4	1948566	resin polyamide polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:44
5	190	(die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) same "5"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:46
6	856	(die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:47
7	339	((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) ) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48

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7	339	((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) ) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48
6	856	((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48
8	223	((((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) ) and solder) and ((silicone with rubber) silicone rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 04:48

L Number	Hits	Search Text	DB	Time stamp
1	247243	polyamide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:19
2	223	((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) ) and solder) and ((silicone with rubber) silicone rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20
3	257783	polyamide amd ( ((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) ) and solder) and ((silicone with rubber) silicone rubber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20
4	44	polyamide and ( ((die chip semiconductor ic (integrated adj circuit) dice ) same (sheet (silicone with rubber) silicone) same (heat with (plate sink radiate radiating radition slug plate dissipate dissipation dissipated)) same (resin polyamide polyimide) ) and solder) and ((silicone with rubber) silicone rubber))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/09 10:20